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## Product Change Notification - JAON-14ZGDV728

**Date:** 19 Jul 2016  
**Product Category:** Memory; Analog (Linear & Mixed Signal) AND Interface  
**Notification subject:** CCB 2701 Initial Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 160K wafer technology available in 8L PDIP package at MMT assembly site  
**Notification text:** **PCN Status:**  
 Initial notification

### Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN\_#\_Affected\_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

### Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 160K wafer technology available in 8L PDIP package at MMT assembly site.

### Pre Change:

Using gold (Au) bond wire

### Post Change:

Using palladium coated copper with gold flash (CuPdAu) bond wire

### Pre and Post Change Summary:

	Pre Change	Post Change
<b>Assembly Site</b>	MMT assembly site	MMT assembly site
<b>Wire material</b>	Au wire	CuPdAu wire
<b>Die attach material</b>	CRM-1064L	CRM-1064L
<b>Molding compound material</b>	GE800	GE800
<b>Lead frame material</b>	CDA194	CDA194

### Impacts to Data Sheet:

None

### Change Impact:

None

### Reason for Change:

To improve manufacturability and qualify Palladium coated copper with gold flash (CuPdAu) bond wire

### Change Implementation Status:

In Progress

**Estimated Qualification Completion Date:  
September 2016**

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date.

**Time Table Summary:**

Workweek	July 2016				->	September 2016				
	27	28	29	30		35	36	37	38	39
Initial PCN Issue Date			X							
Qual Report Availability								X		
Final PCN Issue Date								X		

**Method to Identify Change:**  
Traceability code

**Qualification Plan:**  
Please open the attachments included with this PCN labeled as PCN\_#\_Qual Plan.

**Revision History:**  
**July 19, 2016:** Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

- Attachment(s):**
- [PCN\\_JAON-14ZGDV728\\_Qual\\_Plan.pdf](#)
  - [PCN\\_JAON-14ZGDV728\\_Affected\\_CPN.pdf](#)
  - [PCN\\_JAON-14ZGDV728\\_Affected\\_CPN.xls](#)

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Affected Catalog Part Numbers (CPN)

PCN_JAON-14ZGDV728
CATALOG_PART_NBR
11AA010-I/P
11AA020-I/P
11AA040-I/P
11AA080-I/P
11AA160-I/P
11AA161-I/P
11LC010-E/P
11LC010-I/P
11LC020-E/P
11LC020-I/P
11LC040-E/P
11LC040-I/P
11LC080-E/P
11LC080-I/P
11LC160-E/P
11LC160-I/P
11LC161-E/P
11LC161-I/P
24AA014H-I/P
24AA014-I/P
24AA01H-I/P
24AA01-I/P
24AA02/P
24AA024H-I/P
24AA024-I/P
24AA025-I/P
24AA025UID-I/P
24AA02H-I/P
24AA02-I/P
24AA02UID-I/P
24AA52-I/P
24C01C/P
24C01C-E/P
24C01C-I/P
24C02C/P
24C02C-E/P
24C02C-I/P
24LC014-E/P
24LC014H-E/P
24LC014H-I/P
24LC014-I/P
24LC01B/P
24LC01B-E/P

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Affected Catalog Part Numbers (CPN)

PCN_JAON-14ZGDV728
CATALOG_PART_NBR
24LC01BH-E/P
24LC01BH-I/P
24LC01B-I/P
24LC024/P
24LC024-E/P
24LC024H-E/P
24LC024H-I/P
24LC024-I/P
24LC025/P
24LC025-E/P
24LC025-I/P
24LC02B/P
24LC02B-E/P
24LC02BH-E/P
24LC02BH-I/P
24LC02B-I/P
24LCS52-I/P
24VL014/P
24VL014H/P
24VL024/P
24VL024H/P
24VL025/P
34AA02-E/P
34AA02-I/P
34LC02-E/P
34LC02-I/P
34VL02/P
MCP4726-E/P
MCP7940M-I/P
MCP7940N-I/P